

NC257-2 SOLDER PASTE

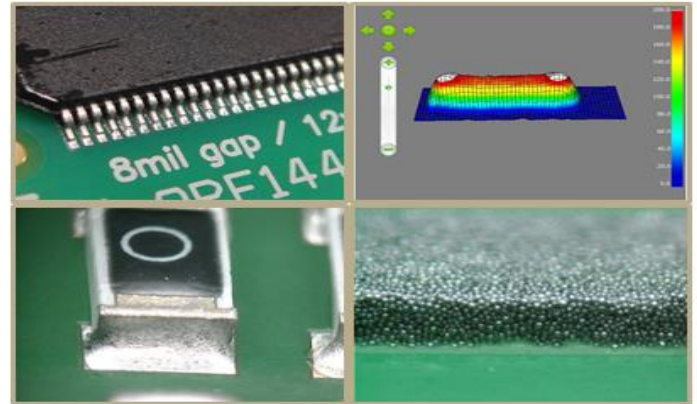
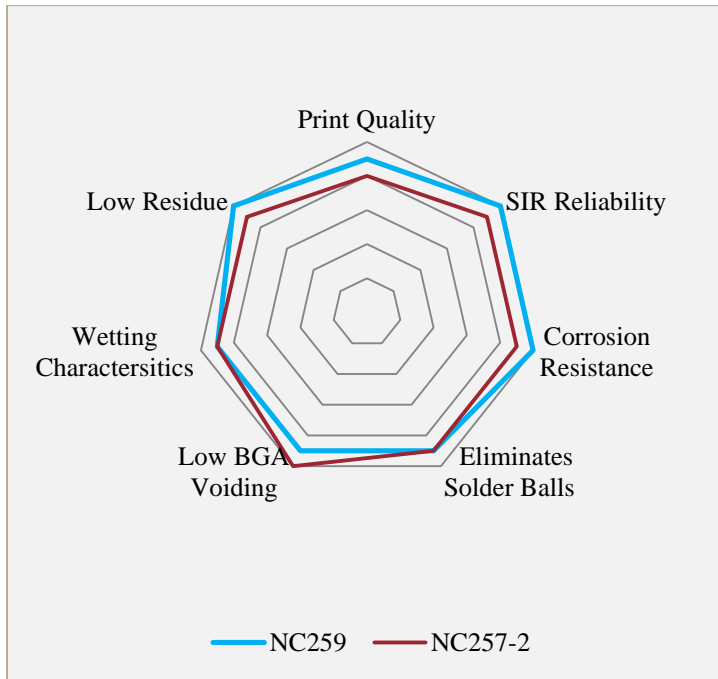
FEATURES

- RoHS Compliant
- Halogen Free
- Reduces Voiding Under Micro-BGAs
- Low Solder Beading
- Excellent Wetting
- Mitigates Head-in-Pillow Defects
- Pin Testable Residues

DESCRIPTION

NC257-2 has been developed to offer extremely broad process windows for printing, wetting and pin-probe testing. NC257-2 produces bright, smooth and shiny solder joints and very clear, low volume post soldering residue. NC257-2 was developed for use in air reflow, but can be used in both N₂ and vapor-phase reflow processes as well. NC257-2 is formulated to extend print performance and tack time in facilities where environmental control is not at its optimum.

CHARACTERISTICS



HANDLING & STORAGE

Alloy	Parameter	Time	Temperature
Lead-Free	Refrigerated Shelf Life	1 year	0°C - 12°C (32°F - 54°F)
Lead-Free	Unrefrigerated Shelf Life	6 months	13°C - 22°C (55°F - 72°F)
Leaded	Refrigerated Shelf Life	9 months	0°C - 12°C (32°F - 54°F)
Leaded	Unrefrigerated Shelf Life	4 months	13°C - 22°C (55°F - 72°F)

Do not add used paste to unused paste. Store used paste separately; keep unused paste tightly sealed with internal plug or end cap in place. See AIM's paste handling guidelines for further information.

CLEANING

Pre-Reflow: AIM DJAW-10 effectively removes NC257-2 solder paste from stencils while in process. DJAW-10 can be hand applied or used in under stencil wipe equipment. Isopropanol (IPA) is not recommended in process, but may be used as a final stencil rinse.

Post-Reflow Flux Residue: NC257-2 residues can remain on the assembly after reflow and do not require cleaning. Where cleaning is mandated, AIM has worked closely with industry partners to ensure that NC257-2 residues can be effectively removed with common defluxing agents. Contact AIM for cleaning compatibility information.

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REFLOW PROFILE

Detailed profile information may be found at <http://www.aimsolder.com/reflow-profile-supplements>. Contact AIM for additional information.

PRINTING

Recommended Initial Printer Settings – Dependent on PCB and Pad Design	
Parameter	Recommended Initial Settings
Squeegee Pressure	0.4 - 0.7kg/25mm
Squeegee Speed	13 – 152 mm/second
Snap-off Distance	On Contact 0.00 mm
PCB Separation Distance	0.75 - 2.0 mm
PCB Separation Speed	3 - 20 mm/second


TEST DATA SUMMARY

Name	Test Method	Results	
IPC Flux Classification	J-STD-004	ROLO	
Name	Test Method	Typical Results	Image
Copper Mirror	J-STD-004 3.4.1.1 IPC-TM-650 2.3.32	LOW	
Corrosion	J-STD-004 3.4.1.2 IPC-TM-650 2.6.15	PASS	<div style="display: flex; justify-content: space-around;"> <div style="text-align: center;"> <p>Before</p>  </div> <div style="text-align: center;"> <p>After</p>  </div> </div>
Oxygen Bomb Halogen Testing	EN14582:2007 SW 9056 SW 5050	Br 585 mg/Kg Cl < 247 mg/Kg	
Qualitative Halides, Silver Chromate	J-STD-004 3.5.1.1 IPC-TM-650 2.3.33	PASS	
Qualitative Halides, Fluoride Spot	J-STD-004 3.5.1.2 IPC-TM-650 2.3.35.1	PASS	
Surface Insulation Resistance	J-STD-004 3.4.1.4 IPC-TM-650 2.6.3.7	PASS	

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TECHNICAL DATA SHEET

Name	Test Method	Typical Results	Image
Electrochemical Migration	J-STD-004 3.4.1.5 IPC-TM-650 2.6.14.1	PASS	
Acid Value Determination	J-STD-004 3.4.2.2 IPC-TM-650 2.3.13	150 mg KOH/ g flux Typical	
Viscosity	J-STD-004 3.4.2.4 IPC-TM-650 2.4.34	500-900 kcps	
Visual	J-STD-004 3.4.2.5	Gray, Smooth, Creamy	
Slump	J-STD-005A 3.6 IPC-TM-650 2.4.35	PASS	
Solder Ball	J-STD-005A 3.7 IPC-TM-650 2.4.43	PASS	
Tack	J-STD-005A 3.8 IPC-TM-650 2.4.44	30 gf Typical	

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